



Material Content Data Sheet



Sales Product Name				IPZ40N04S5-8R4		Issued		20. July 2018	
MA#				MA001338272					
Package				PG-TSDSON-8-32		Weight*		35.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.222	0.63	0.63	6311	6311	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88		
	non noble metal	zinc	7440-66-6	0.012	0.04		353		
	non noble metal	iron	7439-89-6	0.249	0.71		7065		
wire	non noble metal	copper	7440-50-8	10.102	28.69	29.45	286879	294385	
	noble metal	gold	7440-57-5	0.031	0.09	0.09	875	875	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1065	
encapsulation	plastics	epoxy resin	-	1.931	5.48		54834		
	inorganic material	silicondioxide	60676-86-0	16.779	47.63	53.22	476471	532370	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.14	1.14	11367	11367	
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2432	2432	
solder	noble metal	silver	7440-22-4	0.009	0.03		262		
	non noble metal	tin	7440-31-5	0.007	0.02		210		
	non noble metal	lead	7439-92-1	0.353	1.00	1.05	10013	10485	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17		
	non noble metal	zinc	7440-66-6	0.002	0.01		67		
	non noble metal	iron	7439-89-6	0.047	0.13		1334		
heat sink CLIP	non noble metal	copper	7440-50-8	1.908	5.42	5.56	54172	55590	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
heat sink CLIP	non noble metal	iron	7439-89-6	0.073	0.21		2068		
	non noble metal	copper	7440-50-8	2.958	8.40	8.62	83988	86185	
	*deviation	< 10%				Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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